# WEH002004A / WEH002004B PCB Comparison

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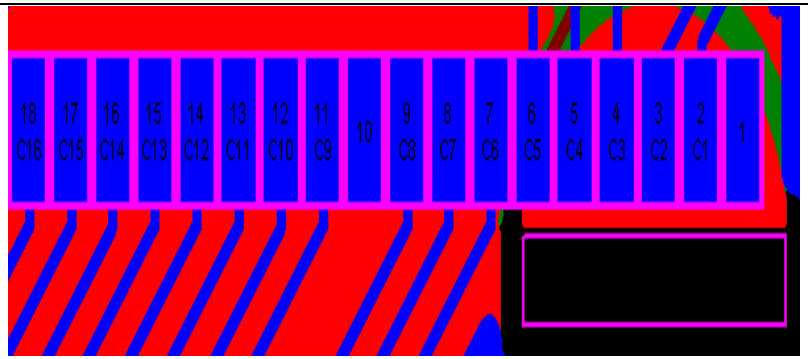
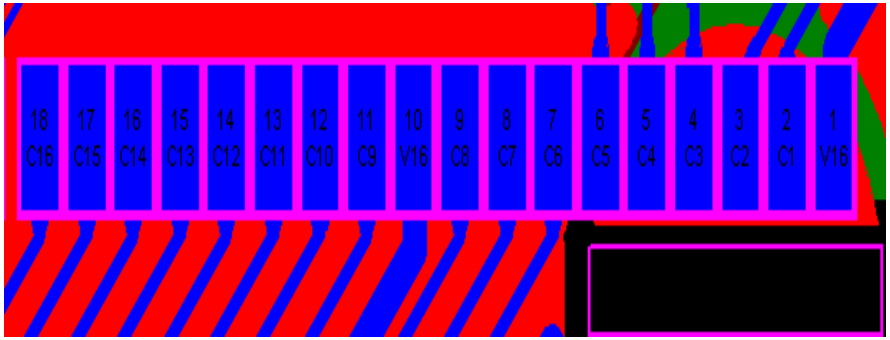
## 一. Reson for Change：

Modify the design of wire path & PAD on the PCB to optimize SMT process yield

## 二. Comparison

| PCB Part No. | EH 2004A REV. C (OLD PCB) | EH 2004A REV. D (NEW PCB) |
|---|---|---|
| 1, Comparison Picture |   |   |
| Difference | **Old Design : C9 is empty PAD** | **New Design : C9 connect to V16 voltage to have better contrast.** |

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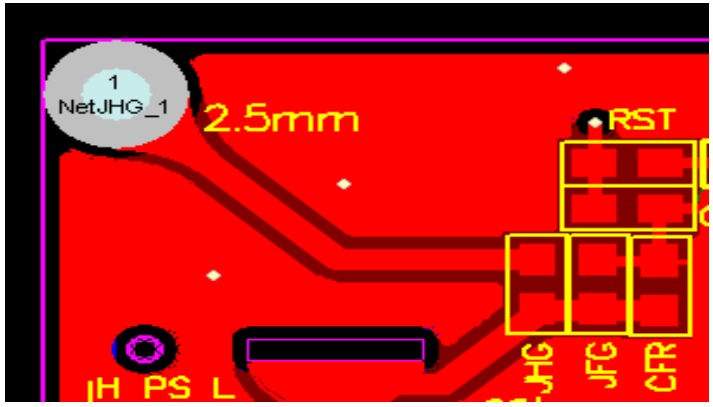
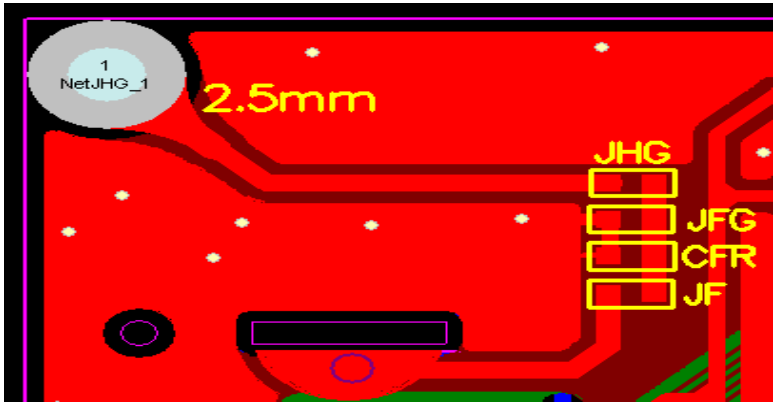
| | | |
|---|---|---|
| 2. Comparison Picture |  |  |
| Difference | **Old Design :**<br>**sharing PAD cause low SMT process yield** | **New Design :**<br>**Modify PAD to isolate each components , increase process yield of SMT** |
| 3. Comparison Picture |  |  |
| Difference | **Old Design : frame directly grounding** | **New Design : add frame grounding pad " JF "** |

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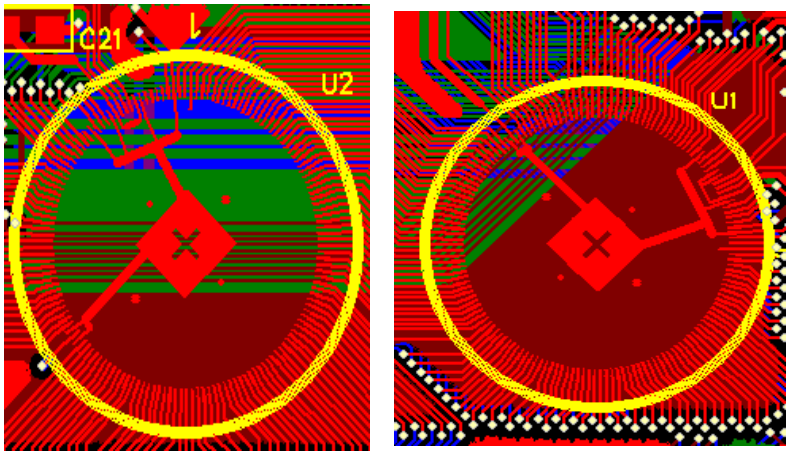
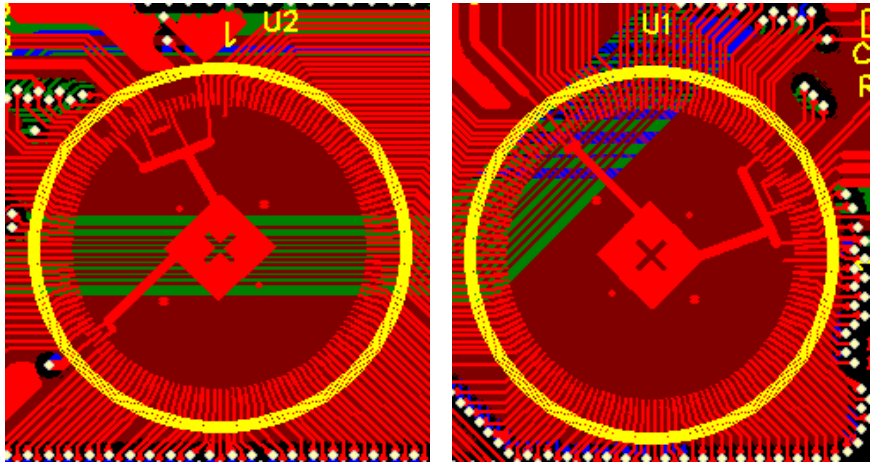
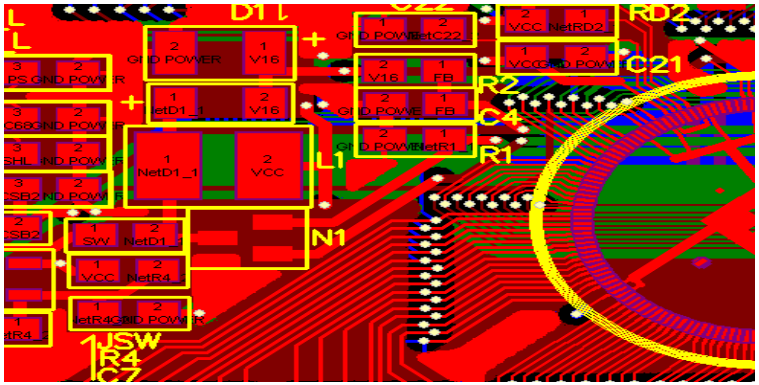
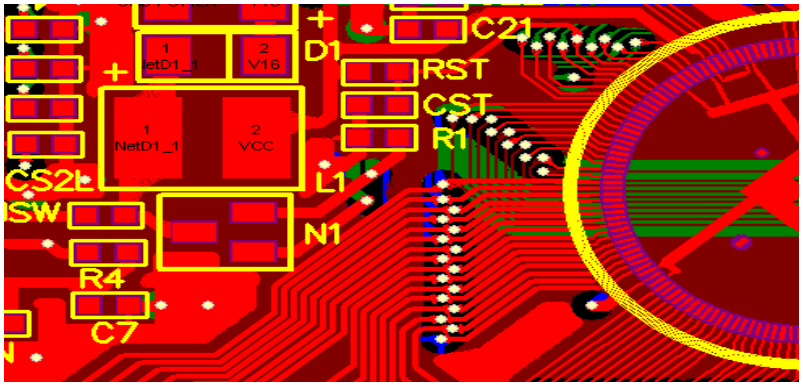
| | | |
|---|---|---|
| 4. Comparison Picture |   |   |
| Difference | **Old version Layout Pad** | **U1 and U2 IC position shift down 0.2mm**<br>**Round white paint frame decrease 0.5mm diameter** |
| 5. Comparison Picture |   |   |
| Difference | **Old version Layout Pad** | **L1 inductance shift down 0.8mm and shift left 0.5mm** |

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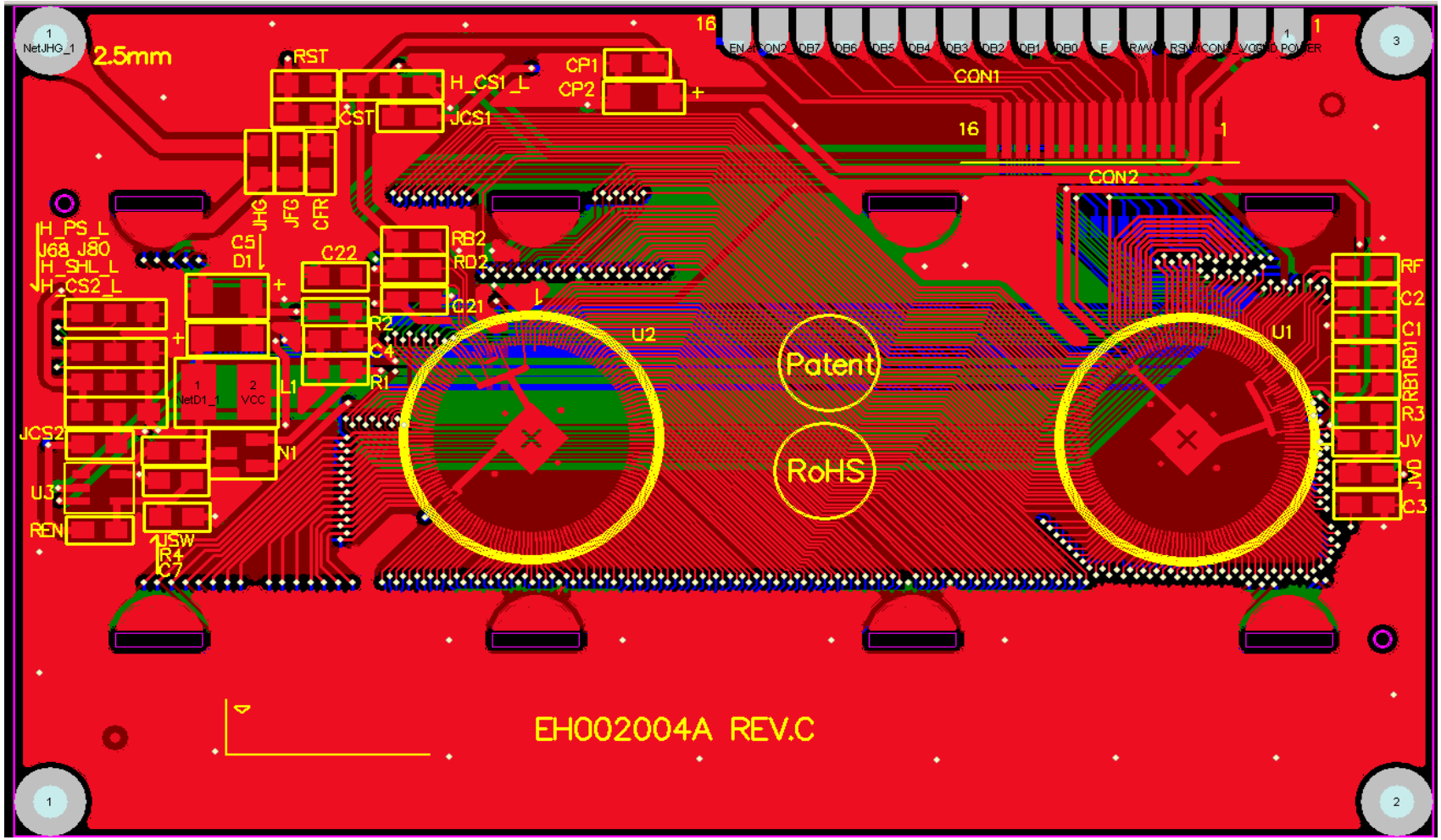
## 三. Overall comparison

### EH 2004A REV. C (OLD PCB) drawing



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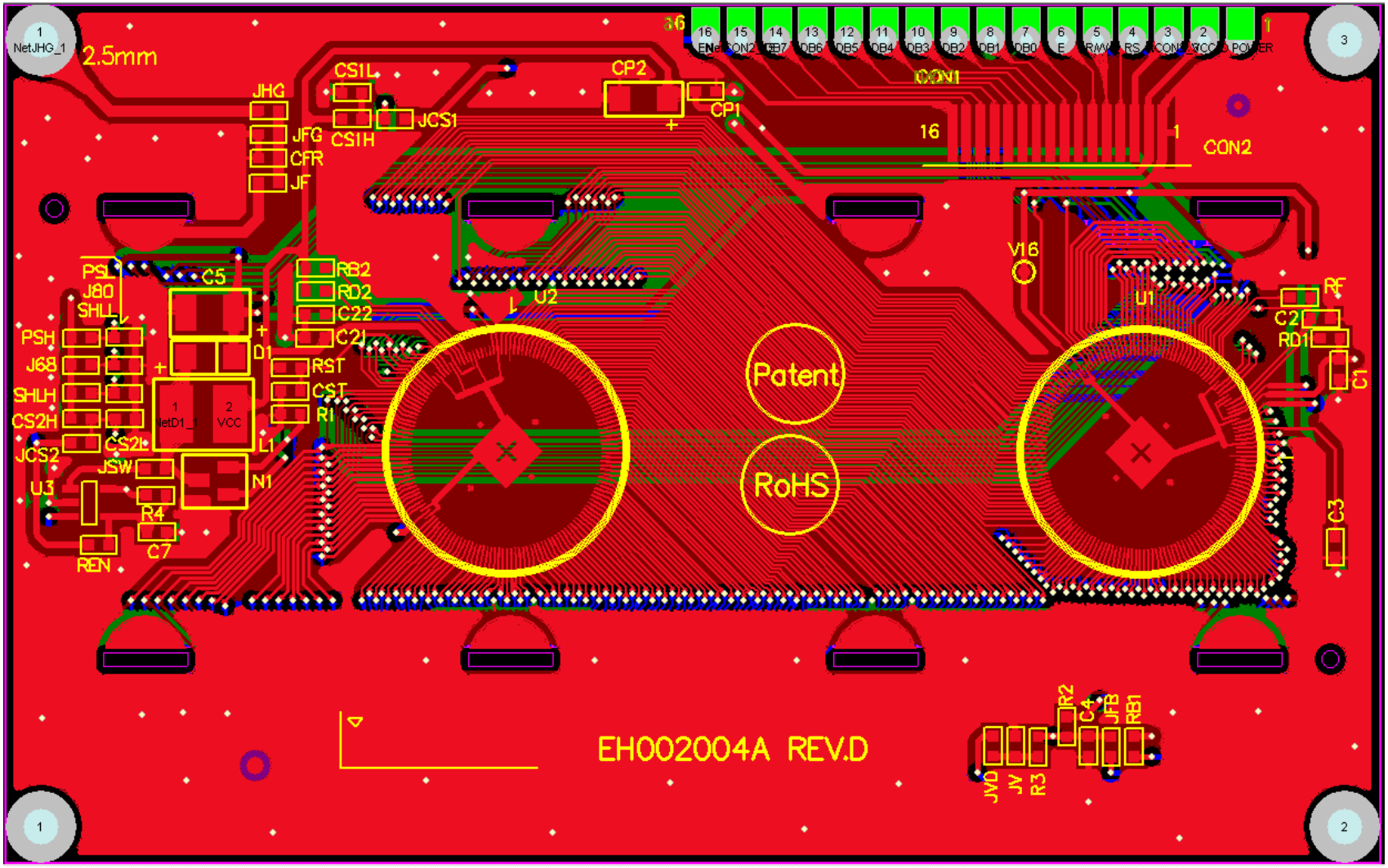
## EH 2004A REV. D (NEW PCB) drawing



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## 四· Conclusion

1. 元件位置變更，請確認

   **the position of components has been changed**

2. 模组电性功能与之前一致，电性对客户的使用无影响。

   **The new version PCB complies with the automation processes and improve yield rate and has better performance. Function & Electrical characteristic remain the same , it won't influences customer using**

**核准: 翟佩峰** **制定:刘晶晶**